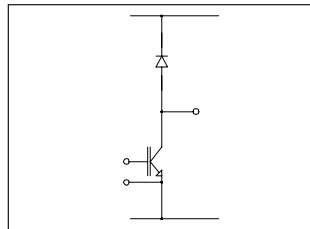


Features

- Gen. 4 Ultrafast Speed IGBT Technology
- HEXFRED™ Diode with UltraSoft Reverse Recovery
- Very Low Conduction and Switching Losses
- Optional SMT Thermistor (NTC)
- Aluminum Nitride DBC
- Very Low Stray Inductance Design for High Speed Operation
- UL approved (file E78996)



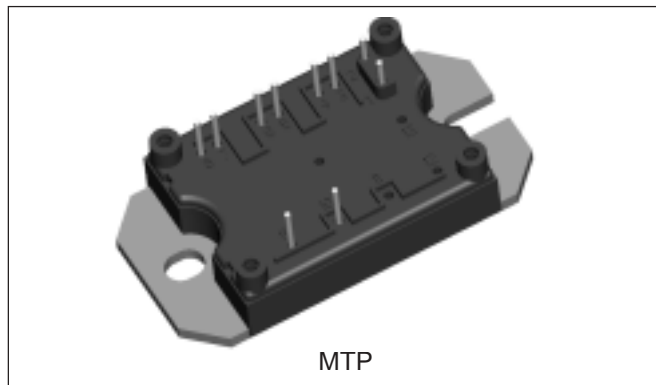
$$V_{CES} = 600V$$

$$I_C = 100A,$$

$$T_C = 25^{\circ}C$$

Benefits

- Optimized for Welding, UPS and SMPS Applications
- Operating Frequencies > 20 kHz Hard Switching, >200 kHz Resonant Mode
- Low EMI, requires Less Snubbing
- Direct Mounting to Heatsink
- PCB Solderable Terminals
- Very Low Junction-to-Case Thermal Resistance



Absolute Maximum Ratings

| Parameters | | Max | Units |
|------------|--|----------------------------|-------|
| V_{CES} | Collector-to-Emitter Voltage | 600 | V |
| I_C | Continuous Collector Current | @ $T_C = 25^{\circ}C$ | 100 |
| | | @ $T_C = 122^{\circ}C$ | 50 |
| I_{CM} | Pulsed Collector Current | 200 | |
| I_{LM} | Peak Switching Current | 200 | |
| I_F | Diode Continuous Forward Current | @ $T_C = 100^{\circ}C$ | 48 |
| I_{FM} | Peak Diode Forward Current | 200 | |
| V_{GE} | Gate-to-Emitter Voltage | ± 20 | V |
| V_{ISOL} | RMS Isolation Voltage, Any Terminal to Case, $t = 1$ min | 2500 | |
| P_D | Maximum Power Dissipation | IGBT @ $T_C = 25^{\circ}C$ | 445 |
| | | @ $T_C = 100^{\circ}C$ | 175 |
| | Diode @ $T_C = 25^{\circ}C$ | 205 | |
| | | @ $T_C = 100^{\circ}C$ | 83 |

Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

| Parameters | | Min | Typ | Max | Units | Test Conditions |
|---------------------------------------|---|-----|------|-------|------------------------|--|
| V _{(BR)CES} | Collector-to-Emitter Breakdown Voltage | 600 | | | V | V _{GE} = 0V, I _C = 250μA |
| V _{CE(on)} | Collector-to-Emitter Voltage | | 1.69 | 2.31 | | V _{GE} = 15V, I _C = 50A |
| | | | 1.96 | 2.55 | | V _{GE} = 15V, I _C = 100A |
| | | | 1.88 | 2.24 | | V _{GE} = 15V, I _C = 100A, T _J = 150°C |
| V _{GE(th)} | Gate Threshold Voltage | 3 | | 6 | I _C = 0.5mA | |
| B _{VR} | Diode Reverse Breakdown Voltage | 600 | | | I _R = 200μA | |
| ΔV _{GE(th)} /ΔT _J | Temperature Coeff. of Threshold Voltage | | - 13 | | mV/°C | V _{CE} = V _{GE} , I _C = 500μA |
| g _{fe} | Forward Transconductance | 22 | 29 | | S | V _{CE} = 50V, I _C = 100A |
| I _{CES} | Collector-to-Emitter Leaking Current | | | 0.25 | mA | V _{GE} = 0V, V _{CE} = 600V |
| | | | | 6 | | V _{GE} = 0V, V _{CE} = 600V, T _J = 150°C |
| V _{FM} | Diode Forward Voltage Drop | | 1.64 | 1.82 | V | I _F = 100A, V _{GE} = 0V |
| | | | 1.56 | 1.74 | | I _F = 100A, V _{GE} = 0V, T _J = 150°C |
| I _{GES} | Gate-to-Emitter Leakage Current | | | ± 250 | nA | V _{GE} = ± 20V |

Switching Characteristics @ T_J = 25°C (unless otherwise specified)

| Parameters | | Min | Typ | Max | Units | Test Conditions |
|-------------------------|---|-----|------|-------|-------|--|
| Q _g | Total Gate Charge (turn-on) | | 370 | 555 | nC | I _C = 100A V _{CC} = 480V V _{GE} = 15V |
| Q _{ge} | Gate-Emitter Charge (turn-on) | | 64 | 96 | | |
| Q _{gc} | Gate-Collector Charge (turn-on) | | 163 | 245 | | |
| E _{on} | Turn-On Switching Loss | | 0.7 | 1.2 | mJ | I _C = 50A, V _{CC} = 480V, V _{GE} = 15V, R _g = 5Ω |
| E _{off} | Turn-Off Switching Loss | | 1.7 | 2.6 | | |
| E _{ts} | Total Switching Loss | | 2.4 | 3.8 | | |
| E _{on} | Turn-On Switching Loss | | 1.1 | 1.7 | mJ | I _C = 50A, V _{CC} = 480V, V _{GE} = 15V R _g = 5Ω, T _J = 125°C |
| E _{off} | Turn-Off Switching Loss | | 2.5 | 3.8 | | |
| E _{ts} | Total Switching Loss | | 3.6 | 5.5 | | |
| C _{ies} | Input Capacitance | | 9800 | 14700 | pF | V _{GE} = 0V V _{CC} = 30V f = 1.0 MHz |
| C _{oes} | Output Capacitance | | 602 | 903 | | |
| C _{res} | Reverse Transfer Capacitance | | 121 | 182 | | |
| C _t | Diode Junction Capacitance | | 118 | 177 | | |
| t _{rr} | Diode Reverse Recovery Time | | 99 | 150 | ns | V _{CC} = 480V, I _C = 50A |
| I _{rr} | Diode Peak Reverse Current | | 6.5 | 9.8 | A | di/dt = 200A/μs |
| Q _{rr} | Diode Recovery Charge | | 320 | 735 | nC | R _g = 5Ω |
| di _(rec) /dt | Diode Peak Rate of Fall of Recovery During t _b | | 236 | | A/μs | |

Thermistor Specifications (50MT060ULST only)

| Parameters | Min | Typ | Max | Units | Test Conditions |
|--|-----|------|-----|-------|--|
| R ₀ ⁽¹⁾ Resistance | | 30 | | kΩ | T ₀ = 25°C |
| β ⁽¹⁾⁽²⁾ Sensitivity index of the thermistor material | | 4000 | | K | T ₀ = 25°C T ₁ = 85°C |

(1) T₀, T₁ are thermistor's temperatures

$$(2) \frac{R_0}{R_1} = \exp \left[\beta \left(\frac{1}{T_0} - \frac{1}{T_1} \right) \right], \text{ Temperatures in kelvin}$$

Thermal- Mechanical Specifications

| Parameters | Min | Typ | Max | Units |
|---|--------|---------|------|-------|
| T _J Operating Junction Temperature Range | - 40 | | 150 | °C |
| T _{STG} Storage Temperature Range | - 40 | | 125 | |
| R _{thJC} Junction-to-Case | IGBT | 0.18 | 0.28 | °C/ W |
| | Diode | 0.4 | 0.6 | |
| R _{thCS} Case-to-Sink (Heatsink Compound Thermal Conductivity = 1 W/mK) | Module | 0.06 | | |
| T Mounting torque to heatsink (3) | | 3 ± 10% | | Nm |
| Wt Weight | | 66 | | g |

(3) A mounting compound is recommended and the torque should be checked after 3 hours to allow for the spread of the compound. Lubricated threads

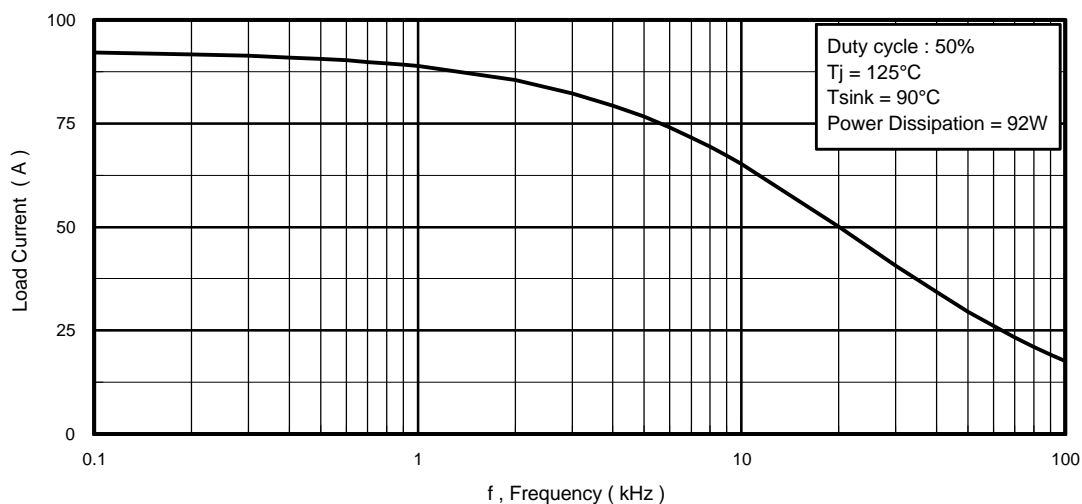


Fig. 1 - Typical Load Current vs. Frequency
(Load Current = I_{RMS} of fundamental)

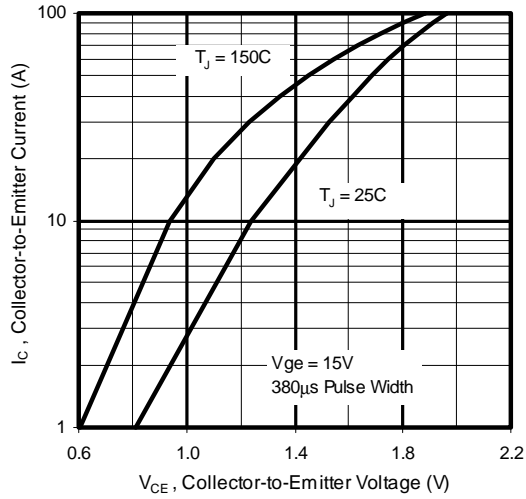


Fig. 2 - Typical Output Characteristics

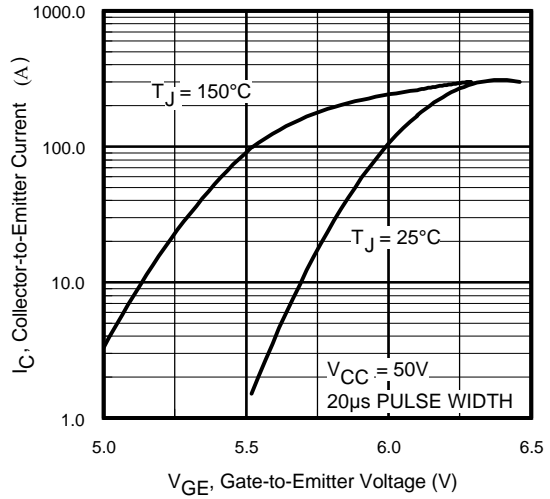


Fig. 3 - Typical Transfer Characteristics

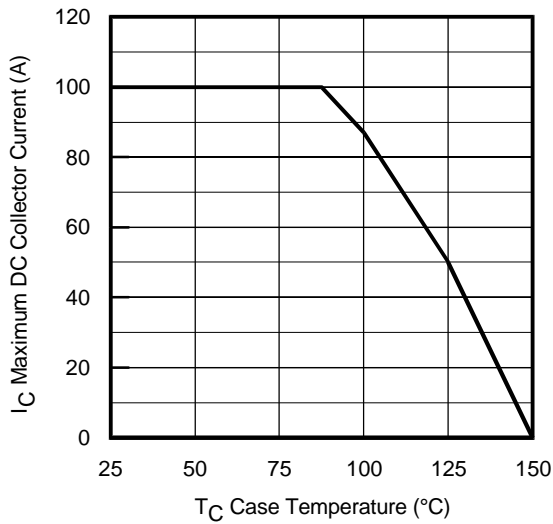


Fig. 4 - Maximum Collector Current vs. Case Temperature

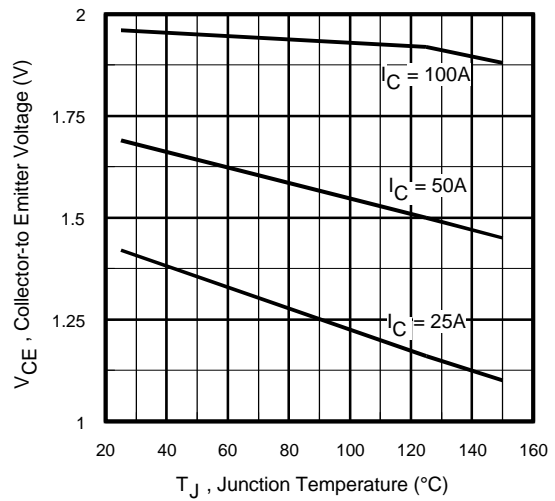


Fig. 5 - Typical Collector-to-Emitter Voltage vs. Junction Temperature

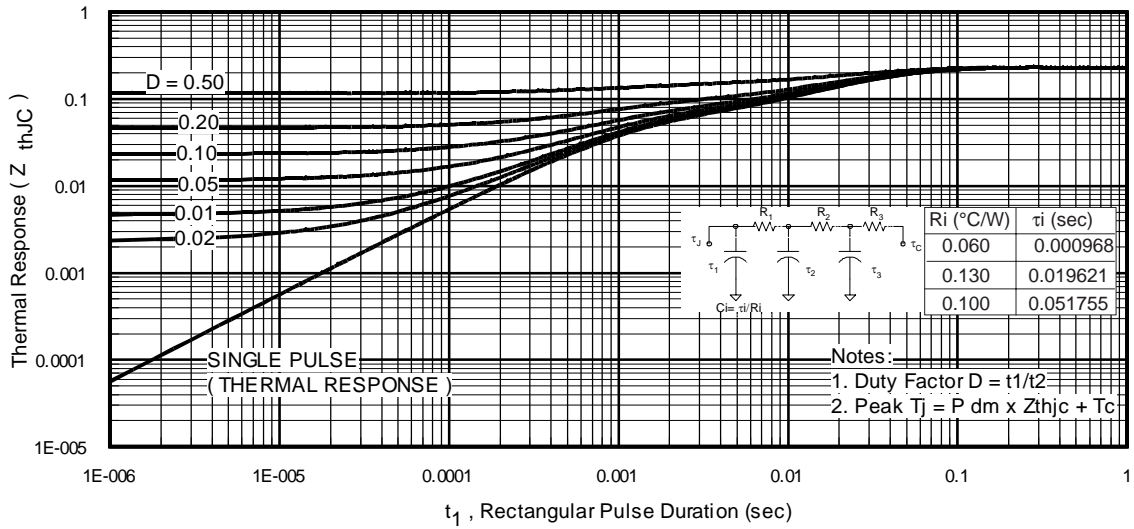


Fig. 6a Maximum Transient Thermal Impedance, Junction-to-Case (IGBT)

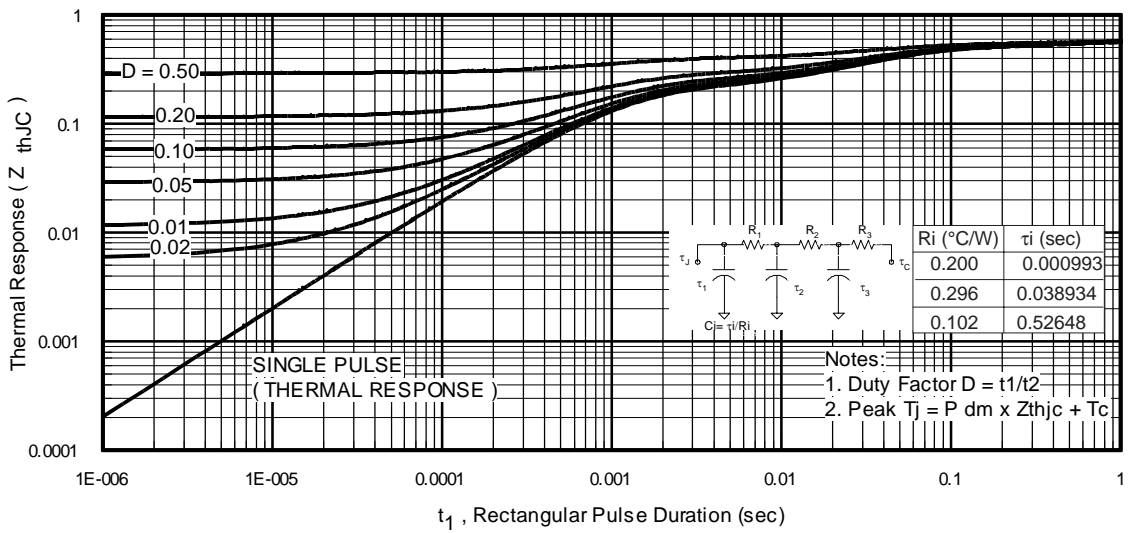


Fig. 6b Maximum Transient Thermal Impedance, Junction-to-Case (DIODE)

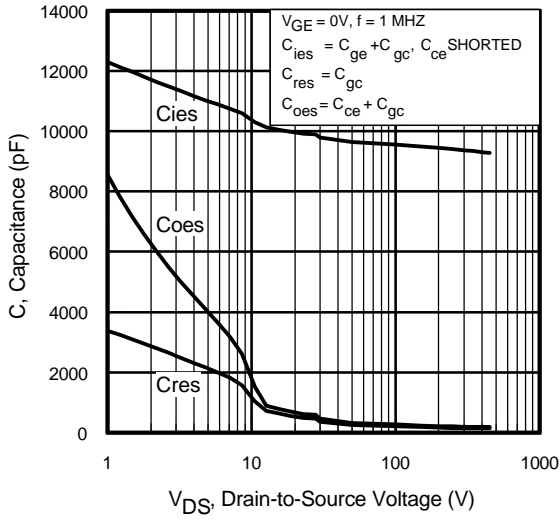


Fig. 7 - Typical Capacitance vs. Collector-to-Emitter Voltage

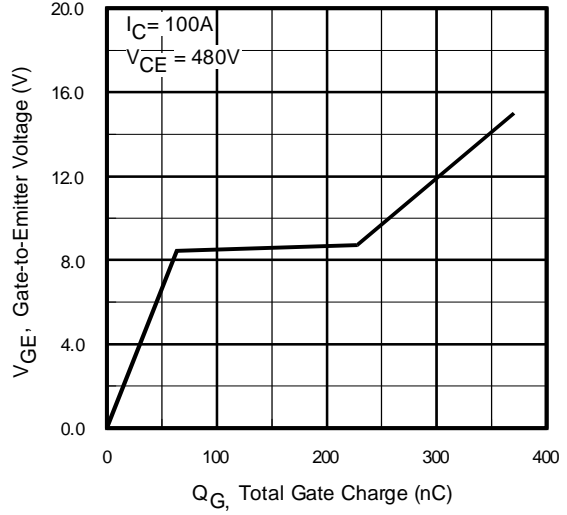


Fig. 8 - Typical Gate Charge vs. Gate-to-Emitter Voltage

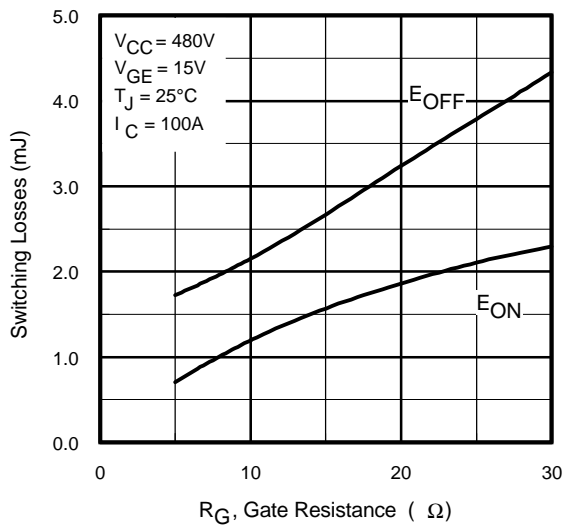


Fig. 9 - Typical Switching Losses vs. Gate Resistance

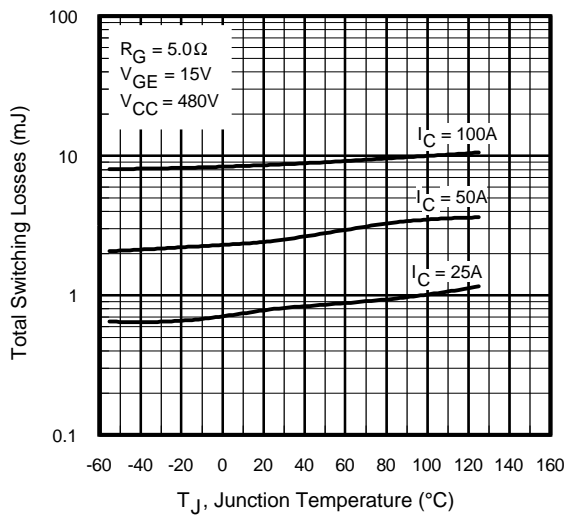


Fig. 10 - Typical Switching Losses vs. Junction Temperature

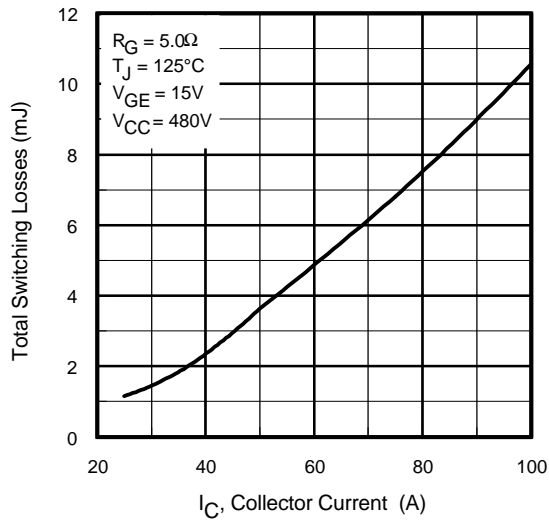


Fig. 11 - Typical Switching Losses vs. Collector-to-Emitter Current

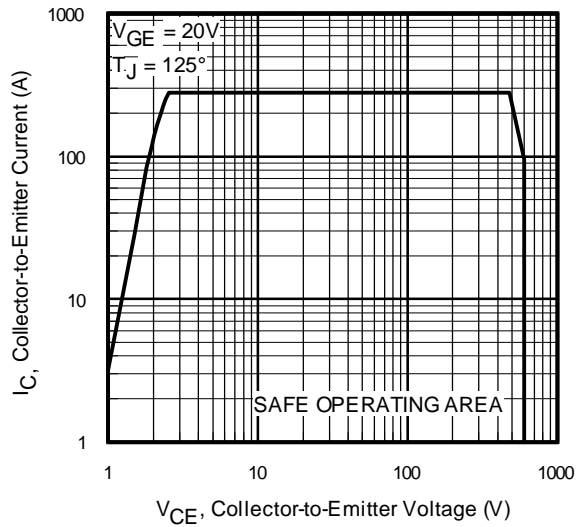


Fig. 12 - Turn-Off SOA

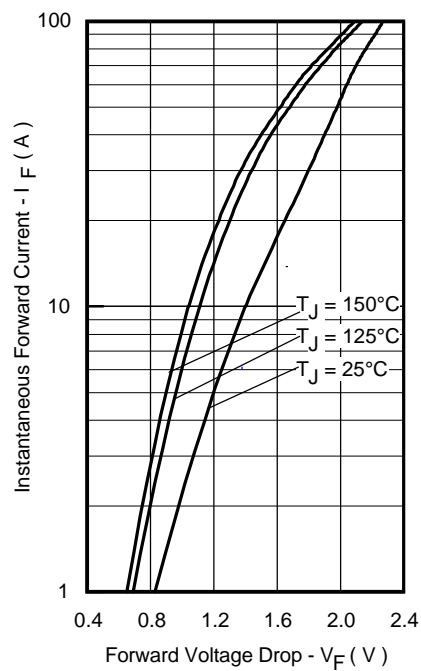


Fig. 13 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

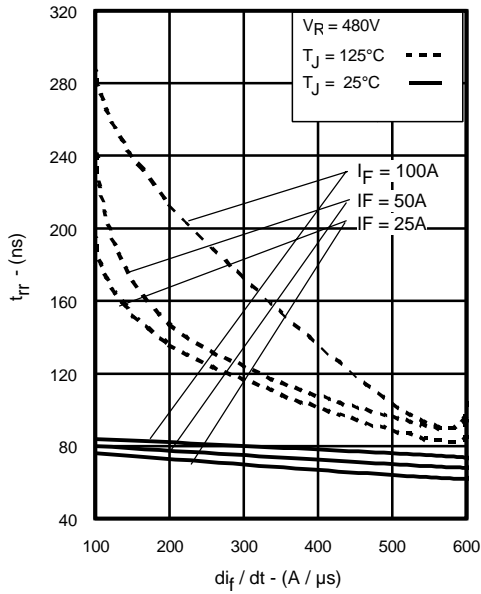


Fig. 14 - Typical Reverse Recovery vs. di_f/dt

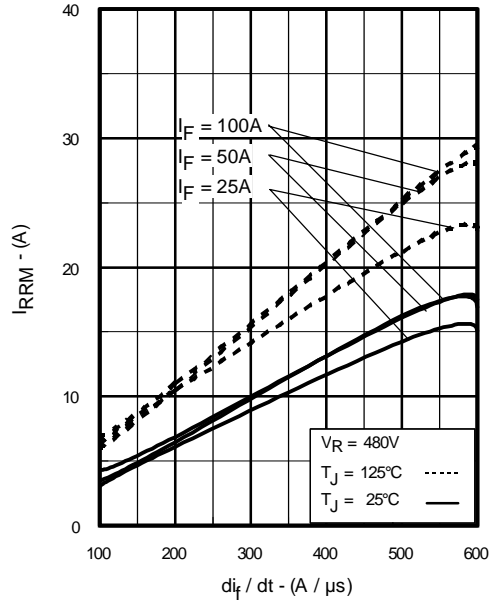


Fig. 15 - Typical Recovery Current vs. di_f/dt

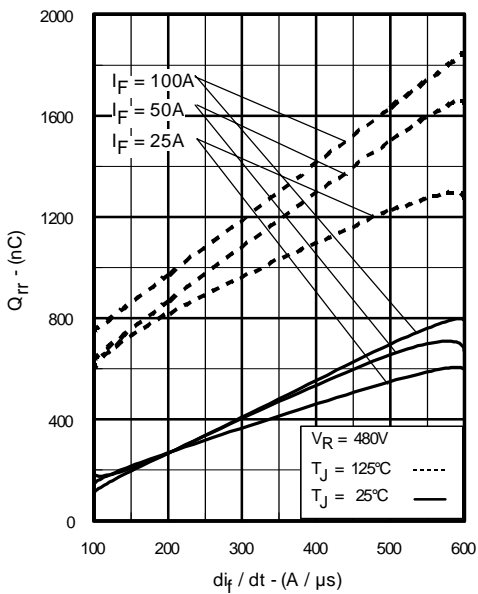


Fig. 16 - Typical Stored Charge vs. di_f/dt

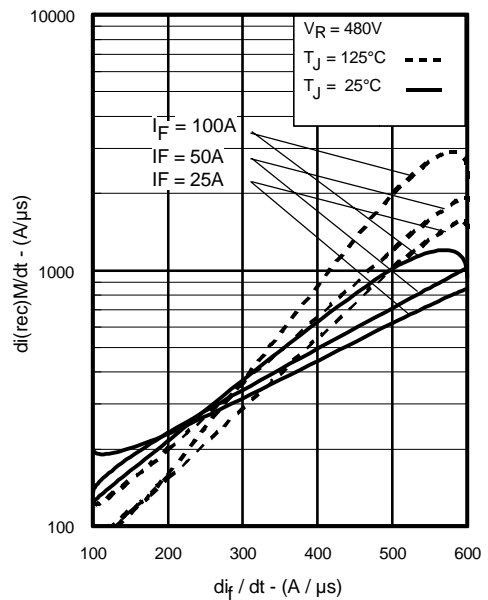
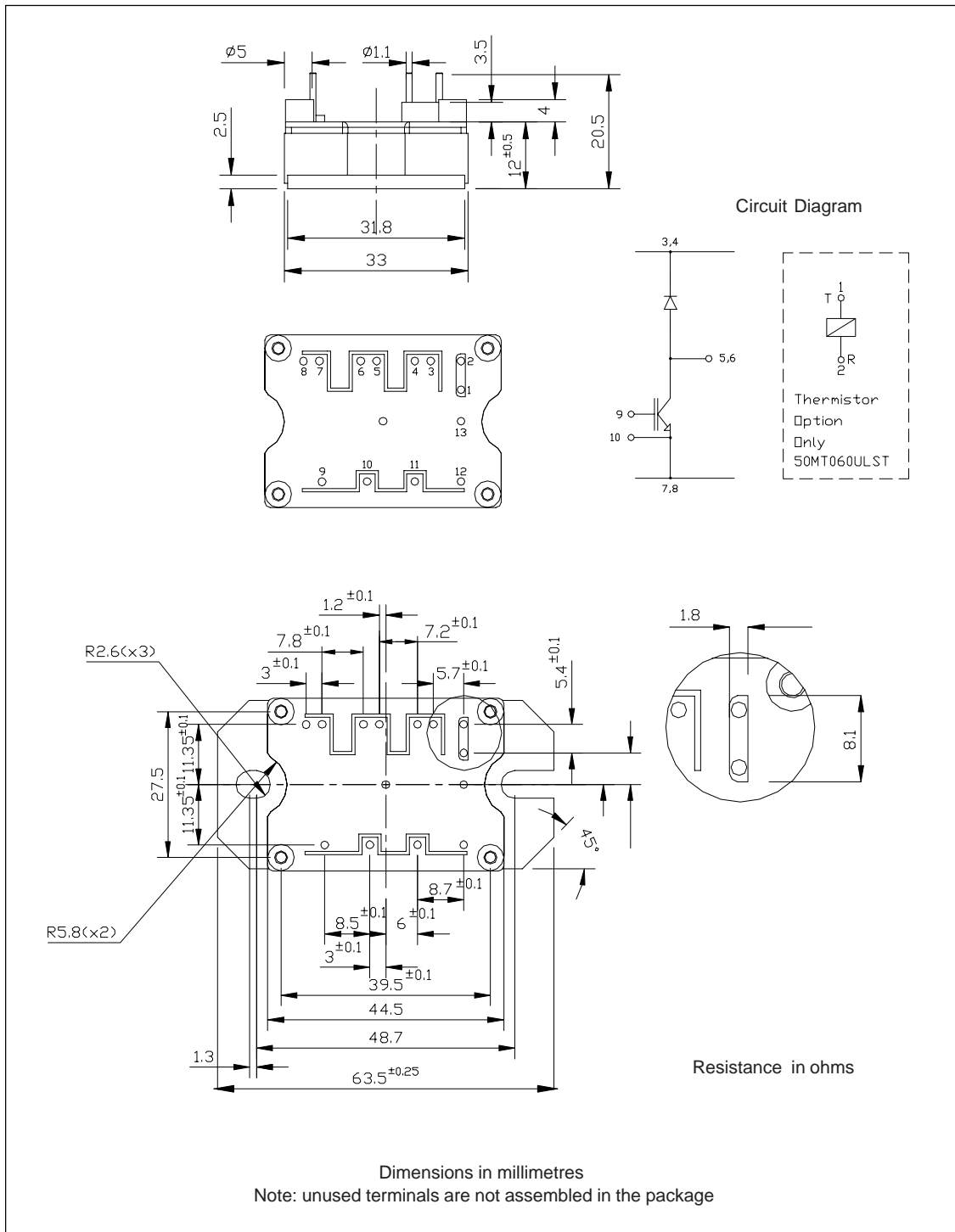


Fig. 17 - Typical $di_{(rec)M}/dt$ vs. di_f/dt

Outline Table



Ordering Information Table

Device Code

| | | | | | |
|----|----|-----|---|----|---|
| 50 | MT | 060 | U | LS | - |
| ① | ② | ③ | ④ | ⑤ | ⑥ |

- 1** - Current rating (50 = 50A)
- 2** - Essential Part Number
- 3** - Voltage code (060 = 600V)
- 4** - Speed/ Type (U = Ultra Fast IGBT)
- 5** - Circuit Configuration (LS = Low Side Chopper)
- 6** - Special Option
 - Empty = no special option
 - T = Thermistor

Data and specifications subject to change without notice.
This product has been designed and qualified for Industrial Level.
Qualification Standards can be found on IR's Web site.